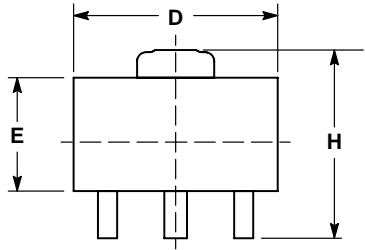
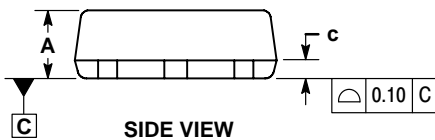


SOT-89, 3 LEAD
CASE 528AG
ISSUE O

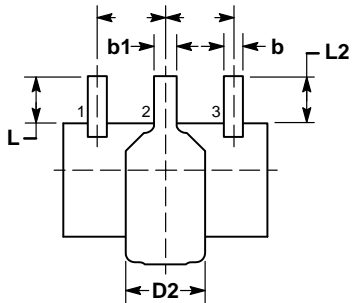
DATE 04 MAR 2014



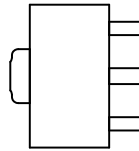
TOP VIEW



SIDE VIEW



BOTTOM VIEW

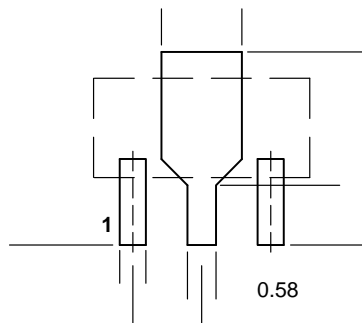


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS INCLUDES LEAD FINISH.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. DIMENSIONS L, L2, D2, AND H ARE MEASURED AT DATUM PLANE C.
6. CENTER LEAD CONTOUR MAY VARY WITHIN THE REGION DEFINED BY DIMENSION E.
7. DIMENSION D2 IS DEFINED AT ITS WIDEST POINT.

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 1.40 | 1.60 |
| b | 0.38 | 0.47 |
| b1 | 0.46 | 0.55 |
| c | 0.40 | 0.44 |
| D | 4.40 | 4.60 |
| D2 | 1.60 | 1.90 |
| E | 2.40 | 2.60 |
| e | | |
| H | 4.05 | 4.25 |
| L | 0.89 | 1.20 |

RECOMMENDED MOUNTING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.